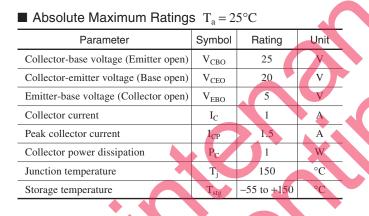
2SC1518

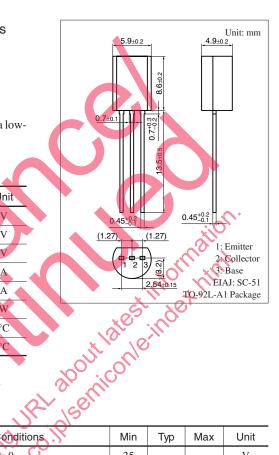
Silicon NPN epitaxial planar type

For high-frequency bias oscillation of tape recorders For DC-DC converter

Features

- Low collector-emitter saturation voltage $V_{CE(sat)}$
- Satisfactory operation performances and high efficiency with a low-voltage power supply





Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

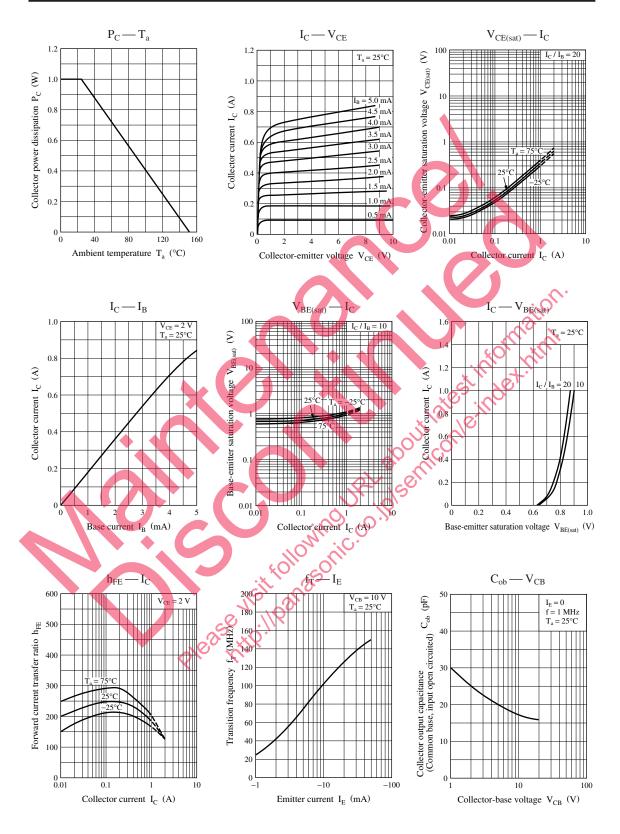
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = 10 \ \mu A \ J_{\rm E} = 0$	25			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = 1$ mÅ, $I_{\rm B} = 0$	20			V
Emitter-base voltage (Collector open)	V _{EBO}	$I_E = 10 \mu A d_C = 0$	5			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 25$ V, $I_E = 0$			100	nA
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = 20 \text{ V}, I_B = 0$			1	μΑ
Forward current transfer ratio	hFE1 *	$V_{CE} = 2 V, I_C = 500 mA$	90		330	_
	h _{FE2}	$V_{CE} = 2 V, I_C = 1 A$	50	100		—
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{C} = 1 \text{ A}, I_{B} = 50 \text{ mA}$			0.5	V
Base-emitter saturation voltage	V _{BE(sat)}	$I_{C} = 500 \text{ mA}, I_{B} = 50 \text{ mA}$			1.2	V
Transition frequency	f _T	$V_{CB} = 10 \text{ V}, I_E = -50 \text{ mA}, f = 200 \text{ MHz}$		150		MHz
Collector output capacitance	C _{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		12	20	pF
(Common base, input open circuited)						

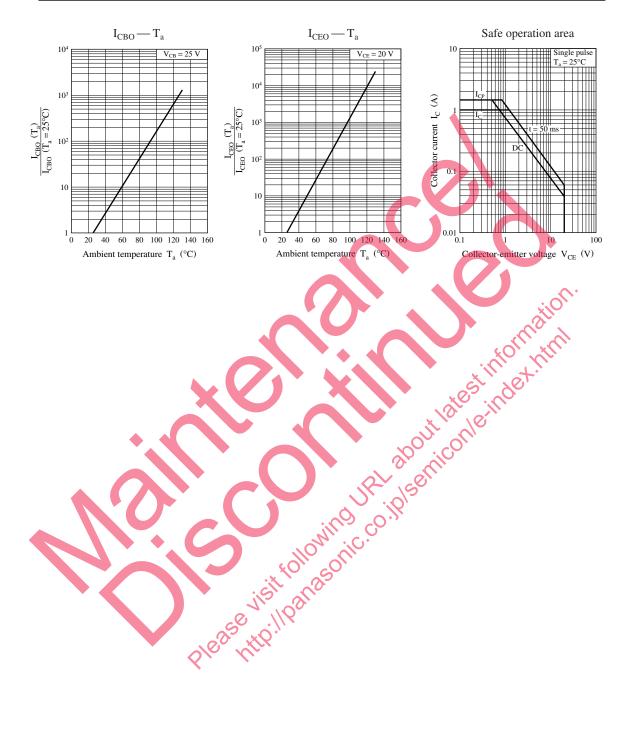
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

Rank	Q	R	S
h _{FE1}	90 to 155	130 to 220	185 to 330

Panasonic





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